Sliding contact switch with rubber fee







Typical Specifications

Ite	ms	Specifications		
Rating (max.)/(min.) (capacitor load)		50mA 16V DC / 10μA 1V DC		
Contact resistance (Initial/After operating life)		200 m Ω max. $/$ 400 m Ω max.		
Operating force		1.96N, 2.45N, 3N		
Operating life	Without load	100,000 cycles		
	With load	100,000 cycles (50mA 16V DC)		

Product Line

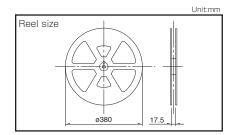
Total travel (mm) Operating force		Poles	Positions	Minimum order unit (pcs.)		Product No.
		1 0165		Japan	Export	Troddet No.
	1.96N	1	1	2,000	8,000	SPEH110101
1.6	2.45N					SPEH120101
	3N					SPEH130103

Packing specifications

Taping

Number of packages (pcs.)			Tape width	Export package	
1 reel	1 case /Japan	1 case /export packing	(mm)	measurements (mm)	
2,000	4,000	8,000	12	393×393×107	

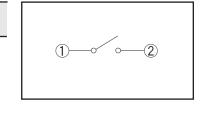
Style

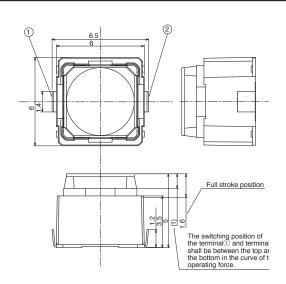


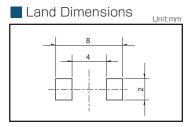
Dimensions

Unit:mm

Circuit Diagram







Series			Vertical					
			SPEH	SPEJ	SPPH4	SPPH1		
Photo			•					
		W	6	7	6.5	10		
Dimensio (mm)	ns	D	6	7	8.5	10		
	Н		5	5.95	8.5			
Tra	vel (mm)		_	_	2.2	1.5		
Total ·	travel (m	m)	1.6	1.7	3	2.5		
Numb	er of pol	es	1		2			
	erating ature rar	nge	-40°C to +90°C	-40℃ to +85℃	−10°C to) +60℃		
Autor	notive us	se	•	•	_	•		
Lit	e cycle		1 3	* 3	★ 3			
Rati (Resi	ng (max. stive loa) d)	50mA 16V DC	0.2A 14V DC	0.1A 30V DC			
	ng (min.) stive loa		10μA 1V DC	_	50μΑ	3V DC		
Durahility	Durability Operating life without load Operating life with load (at max. rated load)		100,000 cycles 400 max.	10,000cycles 150mΩ max.	10,000cycles 100mΩ max.	10,000cycles 40mΩ max.		
Durability			100,000 cycles 400 max.	10,000cycles 150mΩ max.	10,000cycles 100mΩ max.	10,000cycles 40mΩ max.		
	Initial contact resistance		200mΩ max.	150mΩ max.	100mΩ max.	20mΩ max.		
Electrical performance			100MΩ min. 100V DC		100MΩ min. 500V DC			
	Voltag	e proof	250V AC for 1minute		500V AC for 1minute			
		ninal ngth	_	_	5N for	lminute		
Mechanical performance	Actuator strength	Operating direction	50N	49N	30N	50N		
			_	_	10N	_		
	Cold		-40℃ 1000h	-40°C 500h -20°C 96h		96h		
Environmental performance	Dry heat		90℃ 1000h	85°C 500h	Oh 85°C 96h			
	Damp) heat	60℃, 90 to 95%RH 1000h	60°C. 90 to 95%RH 500h 40°C, 90 to 95%RH 96h		95%RH 96h		
	Page 119 120 121			122				

Note

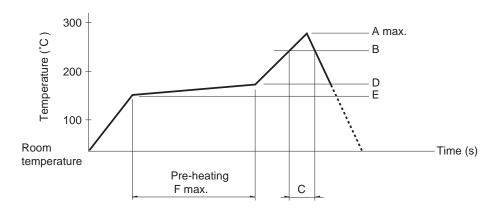
Indicates applicability to all products in the series.

■ Example of Reflow Soldering Condition

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

Push Switches / Soldering Conditions

3. Temperature profile



Series (Reflow type)	A (°C) 3s max.	B (℃)	C (s)	D (℃)	E (℃)	F (s)
SPEJ						
SPEF	260	230	40	180	150	120
SPEH						

Notes

- 1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc.

 The above-stated conditions shall also apply to switch surface temperatures.
- 2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Series	Soldering temperature	Soldering time	
SPPJ3, SPPJ2, SPUN, SPUJ, SPPH4, SPPH1	350±10°C	3+1/0s	
SPED2, SPED4	350±10℃	3±0.5s	
SPEJ	350±10°C	4s max.	
SPEF	350±5℃	3s max.	
SPEH	350℃ max.	3s max.	

Reference for Dip Soldering

(For PC board terminal types)

Series	Ite	ms	Dip soldering		
Jelles	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion	
SPPJ3	100℃ max.	60s max.	260±5℃	5±1s	
SPUN	100℃ max.	60s max.	260±5℃	10±1s	
SPUJ, SPPH4	_		260±5℃	5±1s	
SPPJ2, SPPH1, SPED2, SPED4, SPEF	_		260±5℃	10±1s	